

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
1 IS&R	3	("9107091").PN.	USPAT; JPO; DERMENT	2001/08/30 15:53		
2 BRS	118	chip with (circuit adj layer)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 16:15		
3 BRS	0	((chip with substrate) with (through adj hole)) and (ptfc or stress)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 16:30		
4 BRS	6045	chip and substrate and (through adj hole)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 16:30		
5 BRS	2	(chip and substrate and (through adj hole)) and (ptfc or stress)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 16:31		
6 BRS	871	(chip with substrate) with (through adj hole)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 16:33		
7 BRS	106	(chip with (insulat\$ or dielectric) near substrate)) with (through adj hole)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 17:19		Truncation Overflow. Return string from Server is: 5:359193`
8 BRS	381	((pcb or (dielectric adj substrate)) with (polytetrafluoroethylene or ptfc or stress or relax\$)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 17:47		
9 BRS	45	((pcb or (dielectric adj substrate)) with (polytetrafluoroethylene or ptfc or stress or relax\$)) and ((via or through) near hole)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 17:29		
10 BRS	515	((pcb or (dielectric adj substrate)) and (polytetrafluoroethylene or ptfc or stress or relax\$) and ((through or via) adj hole)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 18:14		
11 BRS	49	((pcb or (dielectric adj substrate)) and (polytetrafluoroethylene or ptfc or stress or relax\$) and ((through or via) adj hole)) and ((stress or relax\$) with layer)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 18:06		
12 BRS	81	257/409.ccls. and wafer	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 18:07		
13 BRS	86	((pcb or (dielectric adj substrate)) and (polytetrafluoroethylene or ptfc or stress or relax\$) and ((through or via) adj hole)) and wafer	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 18:15		
14 BRS	5486	wafer same (polytetrafluoroethylene or ptfc or stress or relax\$)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 18:58		
15 BRS	409	wafer near (polytetrafluoroethylene or ptfc or stress or relax\$)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 18:59		
16 BRS	1	wafer near (polytetrafluoroethylene or ptfc)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 18:58		
17 BRS	0	wafer with (polytetrafluoroethylene or ptfc)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 18:59		
18 BRS	0	wafer same (polytetrafluoroethylene or ptfc)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 18:59		
19 BRS	0	chip with (polytetrafluoroethylene or ptfc)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 19:00		
20 BRS	15	chip with (polytetrafluoroethylene or ptfc)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 19:00		
21 BRS	66	wafer with (polytetrafluoroethylene or ptfc)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 19:02		
22 BRS	5	wafer near (polytetrafluoroethylene or ptfc)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 19:19		
23 BRS	102	wafer with (polytetrafluoroethylene or ptfc)	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 19:19		
24 BRS	379	wafer and (polytetrafluoroethylene or ptfc) and chip	USPAT; US-PGPUB; EPO; JPO; DERMENT; IBM TDB	2001/08/30 19:19		

Errors	
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	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition
25	BRS	361	(wafer and (polytetrafluoroethylene or ptfe) and chip) not (wafer with (polytetrafluoroethylene or ptfe))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/30 19:20		
26	BRS	109	(wafer and (polytetrafluoroethylene or ptfe) and chip) and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/08/30 19:21		

Errors	
25	0
26	0